

ABSTRACT OF THE DISCLOSURE

A flip chip package comprises a substrate, a chip, a plurality of electrically conductive bumps and reinforced bumps. The chip has an active surface having a central area and a peripheral area surrounding the central region. The electrically conductive bumps are disposed at the peripheral region of the chip to electrically connect to the substrate. In addition, the reinforced bumps are disposed at the central area of the chip. In such manner, it can enhance the connection between the chip and the substrate.